Preferred Device

# **Sensitive Gate Silicon Controlled Rectifiers**

## **Reverse Blocking Thyristors**

Annular PNPN devices designed for high volume consumer applications such as relay and lamp drivers, small motor controls, gate drivers for larger thyristors, and sensing and detection circuits. Supplied in an inexpensive plastic TO-92/TO-226AA package which is readily adaptable for use in automatic insertion equipment.

#### Features

- Sensitive Gate Trigger Current 200 μA Maximum
- Low Reverse and Forward Blocking Current 50 μA Maximum,  $T_C = 110^{\circ}C$
- Low Holding Current 5 mA Maximum
- Passivated Surface for Reliability and Uniformity
- Device Marking: Device Type, e.g., 2N5060, Date Code
- Pb-Free Packages are Available\*

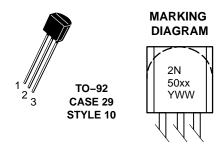


### ON Semiconductor<sup>®</sup>

http://onsemi.com

## SILICON CONTROLLED RECTIFIERS 0.8 A RMS, 30 - 200 V





50xx = Year Υ WW = Work Week

Specific Device Code

PIN ASSIGNMENT		
1	Cathode	
2	Gate	
3	Anode	

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### **MAXIMUM RATINGS** ( $T_J = 25^{\circ}C$ unless otherwise noted)

Rating	Symbol	Value	Unit	
Peak Repetitive Off-State Voltage (Note 1) $(T_J = -40 \text{ to } 110^{\circ}\text{C}, \text{Sine Wave},$ 50 to 60 Hz, Gate Open)2N50602N50612N50622N5064	Vdrm, Vrrm	30 60 100 200	V	
On-State Current RMS (180° Conduction Angles; $T_C = 80^{\circ}C$ )	I <sub>T(RMS)</sub>	0.8	A	
*Average On-State Current (180° Conduction Angles) ( $T_c = 67$ °C) ( $T_c = 102$ °C)	I <sub>T(AV)</sub>	0.51 0.255	A	
*Peak Non-repetitive Surge Current, T <sub>A</sub> = 25°C (1/2 cycle, Sine Wave, 60 Hz)	I <sub>TSM</sub>	10	A	
Circuit Fusing Considerations (t = 8.3 ms)	l <sup>2</sup> t	0.4	A <sup>2</sup> s	
*Average On-State Current (180° Conduction Angles) ( $T_c = 67$ °C) ( $T_c = 102$ °C)	I <sub>T(AV)</sub>	0.51 0.255	A	
*Forward Peak Gate Power (Pulse Width $\leq 1.0 \ \mu sec; T_A = 25^{\circ}C)$	P <sub>GM</sub>	0.1	W	
*Forward Average Gate Power ( $T_A = 25^{\circ}C$ , t = 8.3 ms)	P <sub>G(AV)</sub>	0.01	W	
*Forward Peak Gate Current (Pulse Width $\leq 1.0 \ \mu sec; T_A = 25^{\circ}C)$	I <sub>GM</sub>	1.0	А	
*Reverse Peak Gate Voltage (Pulse Width $\leq 1.0 \ \mu sec; T_A = 25^{\circ}C)$	V <sub>RGM</sub>	5.0	V	
*Operating Junction Temperature Range	Т <sub>Ј</sub>	-40 to +110	°C	
*Storage Temperature Range	T <sub>stg</sub>	-40 to +150	°C	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

V<sub>DRM</sub> and V<sub>RRM</sub> for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
*Thermal Resistance, Junction-to-Case (Note 2)	$R_{ ext{ heta}JC}$	75	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	200	°C/W
*Lead Solder Temperature (Lead Length $\ge 1/16''$ from case, 10 s Max)	-	+230*	°C

2. This measurement is made with the case mounted "flat side down" on a heatsink and held in position by means of a metal clamp over the curved surface.

\*Indicates JEDEC Registered Data.

#### **ELECTRICAL CHARACTERISTICS** ( $T_C = 25^{\circ}C$ unless otherwise noted)

Characteristic		Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS		_	-	-		
*Peak Repetitive Forward or Reverse Blocking Curre (V <sub>AK</sub> = Rated V <sub>DRM</sub> or V <sub>RRM</sub> )	ent (Note 3) T <sub>C</sub> = 25°C T <sub>C</sub> = 110°C	I <sub>DRM</sub> , I <sub>RRM</sub>			10 50	μΑ μΑ
ON CHARACTERISTICS		_	-	-		
*Peak Forward On–State Voltage (Note 4) ( $I_{TM} = 1.2 \text{ A peak} @ T_A = 25^{\circ}C$ )		V <sub>TM</sub>	-	-	1.7	V
Gate Trigger Current (Continuous DC) (Note 5) $*(V_{AK} = 7.0 \text{ Vdc}, R_L = 100 \Omega)$	$T_{C} = 25^{\circ}C$ $T_{C} = -40^{\circ}C$	I <sub>GT</sub>			200 350	μΑ
Gate Trigger Voltage (Continuous DC) (Note 5) $*(V_{AK} = 7.0 \text{ Vdc}, R_L = 100 \Omega)$	$T_C = 25^{\circ}C$ $T_C = -40^{\circ}C$	V <sub>GT</sub>		-	0.8 1.2	V
*Gate Non–Trigger Voltage ( $V_{AK}$ = Rated $V_{DRM}$ , $R_L$ = 100 $\Omega$ ) $T_C$ = 110°C		V <sub>GD</sub>	0.1	_	_	V
Holding Current (Note 5) *(V <sub>AK</sub> = 7.0 Vdc, initiating current = 20 mA)	$T_C = 25^{\circ}C$ $T_C = -40^{\circ}C$	ι <sub>Η</sub>	-		5.0 10	mA
Turn-On Time Delay Time Rise Time $(I_{GT} = 1.0 \text{ mA}, V_D = \text{Rated } V_{DRM},$ Forward Current = 1.0 A, di/dt = 6.0 A/ $\mu$ s		t <sub>d</sub> t <sub>r</sub>	-	3.0 0.2	-	μs
$\label{eq:constraint} \begin{array}{l} \mbox{Turn-Off Time} \\ \mbox{(Forward Current = 1.0 A pulse,} \\ \mbox{Pulse Width = 50 } \mu s, \\ \mbox{0.1\% Duty Cycle, di/dt = 6.0 A/} \mu s, \\ \mbox{dv/dt = 20 V/} \mu s, \mbox{I}_{GT} = 1 \mbox{ mA}) \\ \mbox{2N5060, 2} \\ \mbox{2N5062, 2} \end{array}$		tq		10 30		μs

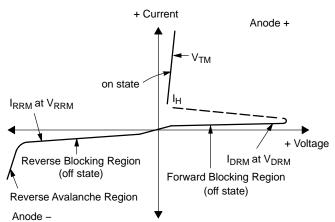
#### DYNAMIC CHARACTERISTICS

Critical Rate of Rise of Off–State Voltage (Rated V <sub>DRM</sub> , Exponential)	dv/dt	-	30	-	V/μs
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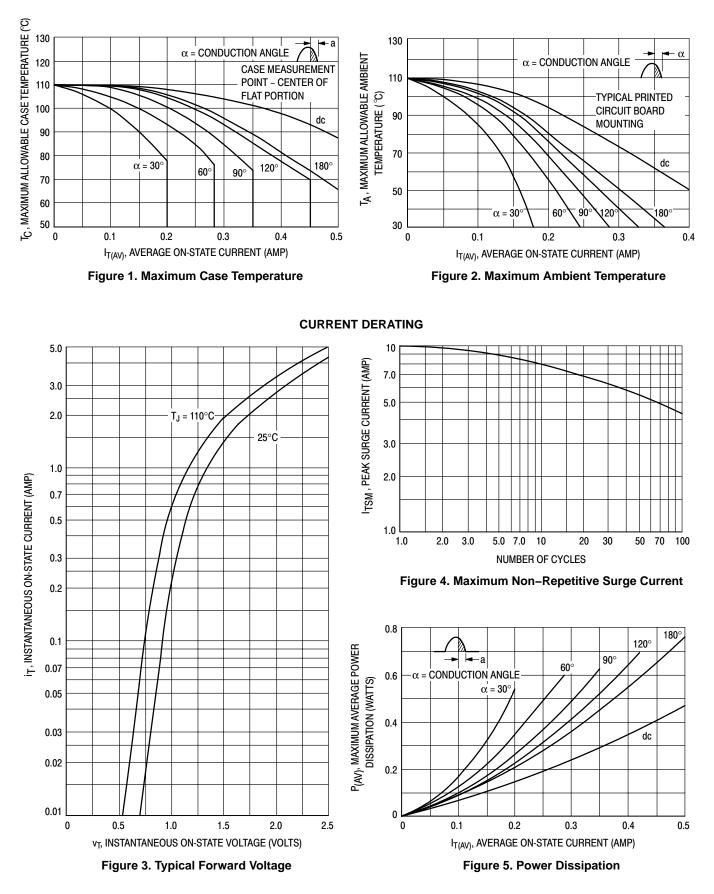
3.  $R_{GK} = 1000 \Omega$  is included in measurement. 4. Forward current applied for 1 ms maximum duration, duty cycle  $\leq 1\%$ . 5.  $R_{GK}$  current is not included in measurement. \*Indicates JEDEC Registered Data.

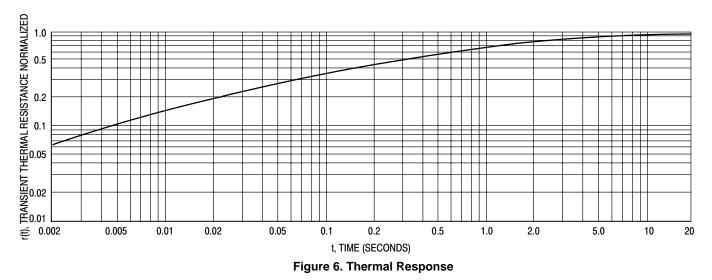
### Voltage Current Characteristic of SCR

Symbol	Parameter
V <sub>DRM</sub>	Peak Repetitive Off State Forward Voltage
I <sub>DRM</sub>	Peak Forward Blocking Current
V <sub>RRM</sub>	Peak Repetitive Off State Reverse Voltage
I <sub>RRM</sub>	Peak Reverse Blocking Current
V <sub>TM</sub>	Peak on State Voltage
Ι <sub>Η</sub>	Holding Current

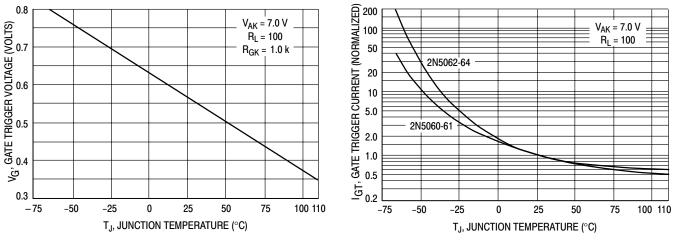


#### **CURRENT DERATING**



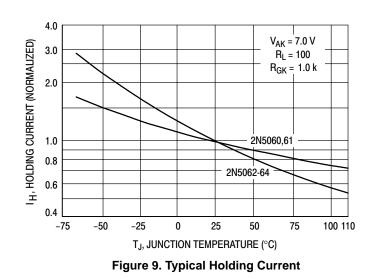












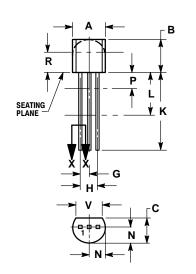
#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
2N5060	TO-92	5,000 Units / Box
2N5060RLRA	TO-92	2,000 / Tape & Reel
2N5060RLRAG	TO-92 (Pb-Free)	2,000 / Tape & Reel
2N5060RLRM	TO-92	2,000 / Ammo Pack
2N5061	TO-92	5,000 Units / Box
2N5061G	TO–92 (Pb–Free)	5,000 Units / Box
2N5061RLRA	TO-92	2,000 / Tape & Reel
2N5061RLRAG	TO–92 (Pb–Free)	2,000 / Tape & Reel
2N5061RLRM	TO-92	2,000 / Ammo Pack
2N5062	TO-92	5,000 Units / Box
2N5062G	TO–92 (Pb–Free)	5,000 Units / Box
2N5062RLRA	TO-92	2,000 / Tape & Reel
2N5062RLRAG	TO–92 (Pb–Free)	2,000 / Tape & Reel
2N5064	TO-92	5,000 Units / Box
2N5064RLRA	TO-92	2,000 / Tape & Reel
2N5064RLRM	TO-92	2,000 / Ammo Pack
2N5064RLRMG	TO–92 (Pb–Free)	2,000 / Ammo Pack
2N5060RL1	TO-92	2,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### PACKAGE DIMENSIONS

TO-92 **TO-226AA** CASE 29-11 **ISSUE AL** 





- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED. 4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.20
В	0.170	0.210	4.32	5.33
С	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
Κ	0.500		12.70	
L	0.250		6.35	
Ν	0.080	0.105	2.04	2.66
Ρ		0.100		2.54
R	0.115		2.93	
٧	0.135		3.43	

STYLE 10: PIN 1. CATHODE 2. GATE 3. ANODE

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